

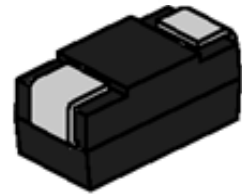


SM1K Series Transient Voltage Suppressor

Rev.4.2

FEATURES:

- ✧ Excellent clamping capability.
- ✧ Low profile package and low inductance.
- ✧ High peak pulse current at 8/20μs waveform.
- ✧ Fast response time: typically less than 1.0ps from 0V to V_{BR} min.
- ✧ High temperature soldering: 260°C/40s at terminals.
- ✧ Plastic package has underwriters laboratory flammability 94V-0.
- ✧ Meets MSL level 1, per J-STD-020, LF maximum peak of 260°C.
- ✧ Terminal: solder plated, solderable per J-STD-002.
- ✧ For surface mounted applications in order to optimize board space.
- ✧ UL 497B item recognized. (File No.: E480698).
- ✧ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact).



SMB

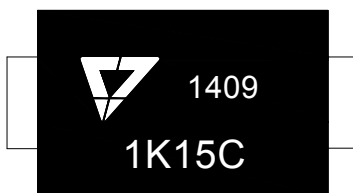


Bi-directional
Symbol

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T _{STG}	-55 to +150	°C
Operating junction temperature range	T _J	-55 to +150	°C
Steady state power dissipation at T _L =75°C	P _{M(AV)}	5.0	W
Peak pulse current at 8/20μs waveform	I _{PP}	1000	A

MARKING



1K15C : Device Marking Code
1409: In ninth week, 2014

ELECTRICAL CHARACTERISTICS(T_A=25℃)

Part Number	Marking Code	V _R	I _R @V _R	V _{BR} @I _T		I _T	V _C @I _{PP}	I _{PP} ^①
Bi-Polar		V	max(μA)	min(V)	max(V)	mA	max(V)	A
SM1K15C	1K15C	15	1	16.7	18.5	1	32	1000
SM1K16C	1K16C	16	1	17.8	19.7	1	34	1000
☆SM1K18C	1K18C	18	1	20.0	22.3	1	37	1000
☆SM1K20C	1K20C	20	1	22.0	24.5	1	40	1000

① Surge waveform: 8/20μs

V_R: Stand-off voltage -- Maximum voltage that can be applied

V_{BR}: Breakdown voltage

V_C: Clamping voltage -- Peak voltage measured across the suppressor at a specified I_{PP}

I_R: Reverse leakage current

☆: Products with negative resistance

ORDERING INFORMATION

SM1K	XX	C
Surface mount 8/20μs 1kA	V _R Voltage	C: Bi-directional

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25℃, unless otherwise noted)

FIG.1:V- I curve characteristics (Bi-directional)

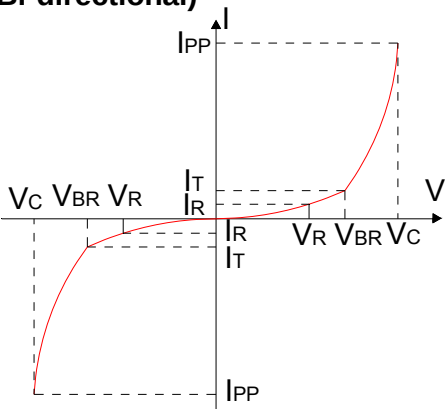


FIG.2:V- I curve characteristics (Bi-directional with negative resistance)

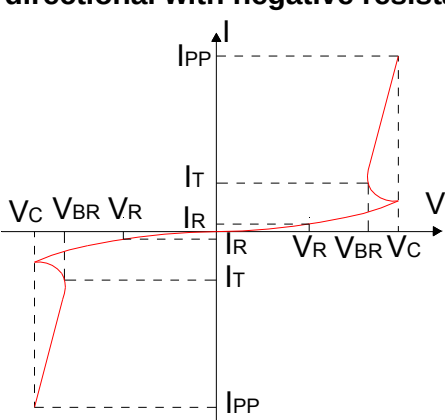


FIG.3: Pulse waveform

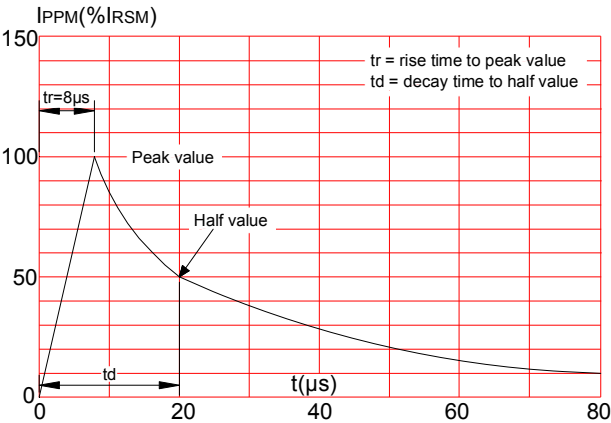
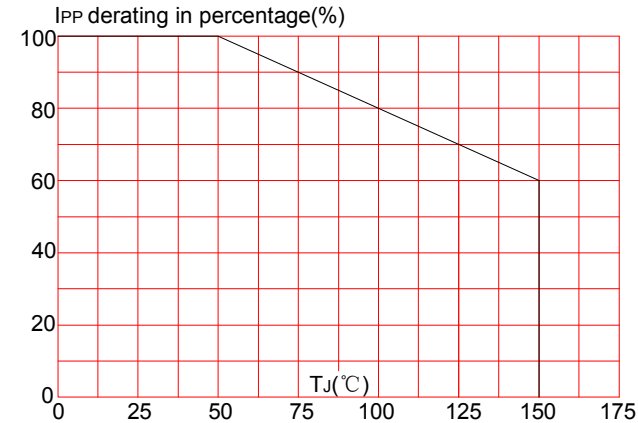
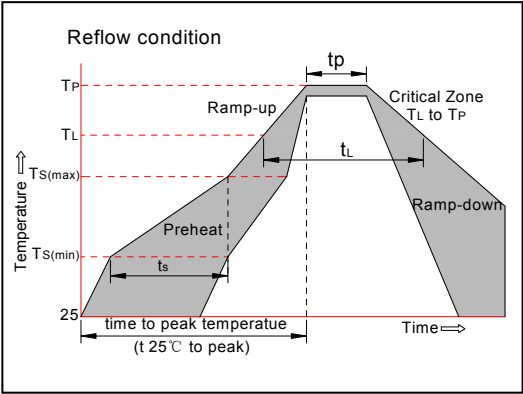


FIG.4: Pulse derating curve

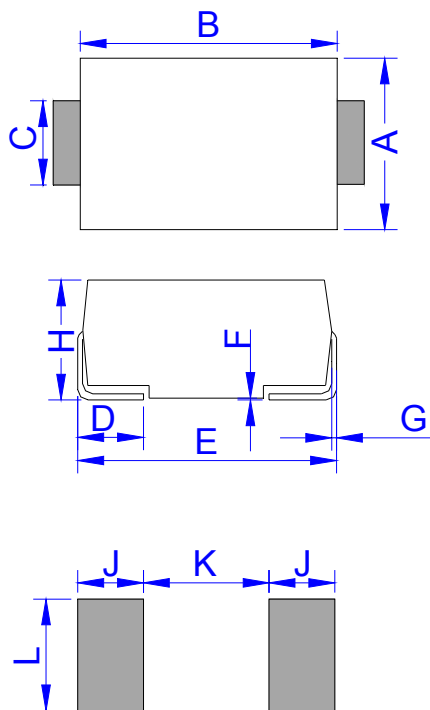


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (Ts(min))	+150°C
	-Temperature Max(Ts(max))	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (TL)to peak)		3°C/sec. Max
Ts(max) to TL - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(TL)(Liquidus)	+217°C
	-Temperature(tL)	60-150 secs.
Peak Temp (Tp)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (tp)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (TP)		8 min. Max
Do not exceed		+260°C



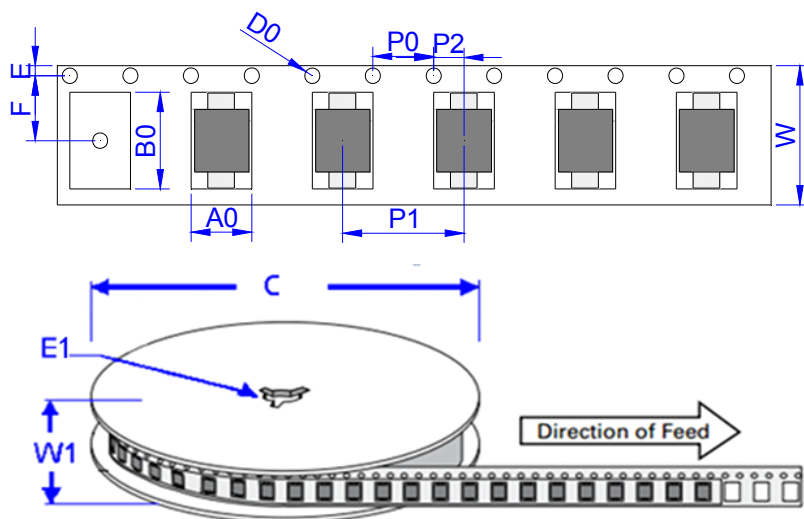
PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.30	4.80	0.169	0.189
C	1.90	2.20	0.075	0.087
D	0.95	1.52	0.037	0.060
E	5.20	5.60	0.205	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.10	2.40	0.083	0.094
J	2.20		0.087	
K		2.60		0.102
L	2.30		0.091	

TAPE AND REEL SPECIFICATION-SMB



Ref.	Dimensions	
	Millimeters	Inches
A0	3.76 ± 0.3	0.148 ± 0.012
B0	5.69 ± 0.3	0.224 ± 0.012
C	330.0	13.0
D0	1.55 ± 0.1	0.061 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3 ± 0.3	0.524 ± 0.012
F	5.5 ± 0.2	0.217 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	8.00 ± 0.2	0.3145 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	12.0 ± 0.2	0.472 ± 0.008
W1	15.7 ± 2.0	0.618 ± 0.079

PART No.	UNIT WEIGHT (g/PCS) typ.	REEL (PCS)	PER CARTON (PCS)	DESCRIPTION
SM1KxxC	0.098	3,000	48,000	13 inch reel pack

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